

## Full Wafer & Singulated Die / Module Test System

### High Throughput Burn-in and Test Solution for Logic/ Memory/Photonic Devices



#### SYSTEM BENEFITS

- **Flexible Solution for High Throughput Burn-in and Test**
  - ◆ Full wafer / panel / singulated die / module burn-in for highest production throughput
  - ◆ Improves yield of logic/memory/photonic die before final package integration
  - ◆ High volume production capacity - up to 18 wafers or panels using WaferPak™ cartridges or 9 singulated die/module DiePak® carriers per chamber
- **Cost-Effective Solution Designed for High Volume Burn-in/Production Test**
  - ◆ Configurable channel resources per Blade (slot): Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
  - ◆ Up to 2,048 "Universal Channel" resources: (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory per channel for test of devices with BIST/DFT
  - ◆ Up to 1,024 high voltage (29V) or high current (4A) sources resources per Blade
- **Production Proven Full-Wafer Burn-in & Test Solution**
  - ◆ Reduces test costs by functionally testing wafers/die/modules during burn-in
  - ◆ Offers a total burn-in and test solution when configured with a WaferPak contactor / DiePak carrier and Wafer Aligner / DiePak Loader
  - ◆ Protects devices with individual per channel over-current and over-voltage protection

*"Setting the Test Standard for Tomorrow"*

#### CORPORATE HEADQUARTERS

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